

IN THE SPECIFICATION:

Please amend the title as follows:

TAPE ATTACHMENT CHIP-ON-BOARD ASSEMBLIES

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity.

Please amend the claims as follows:

Sub C1 → 1. (Twice Amended) A semiconductor die assembly comprising:
a semiconductor substrate having a first surface and a second surface, wherein said semiconductor substrate includes at least one opening defined therethrough between said semiconductor substrate first surface and said semiconductor substrate second surface;
at least one semiconductor die having an active surface with at least one electrical connection area disposed on said semiconductor die active surface, said at least one semiconductor die oriented having said at least one electrical connection area substantially aligned with said at least one semiconductor substrate opening; and
at least one adhesive tape interposed between and attaching said semiconductor die active surface and said semiconductor substrate first surface, wherein a width of said at least one adhesive tape extends at least proximate an edge of said at least one semiconductor die to at least proximate an edge of said at least one semiconductor substrate opening.

DI 2. (Previously Amended) The semiconductor die assembly of claim 1, wherein said width of said at least one adhesive tape extends beyond said edge of said at least one semiconductor substrate opening a distance into said at least one semiconductor substrate opening to provide a detectable surface within said at least one semiconductor substrate opening.